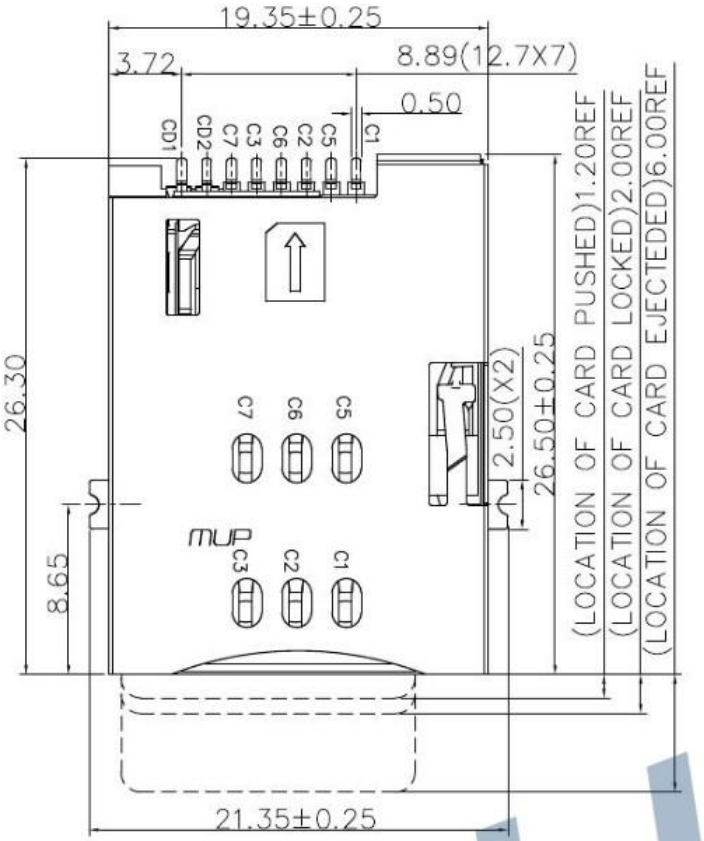
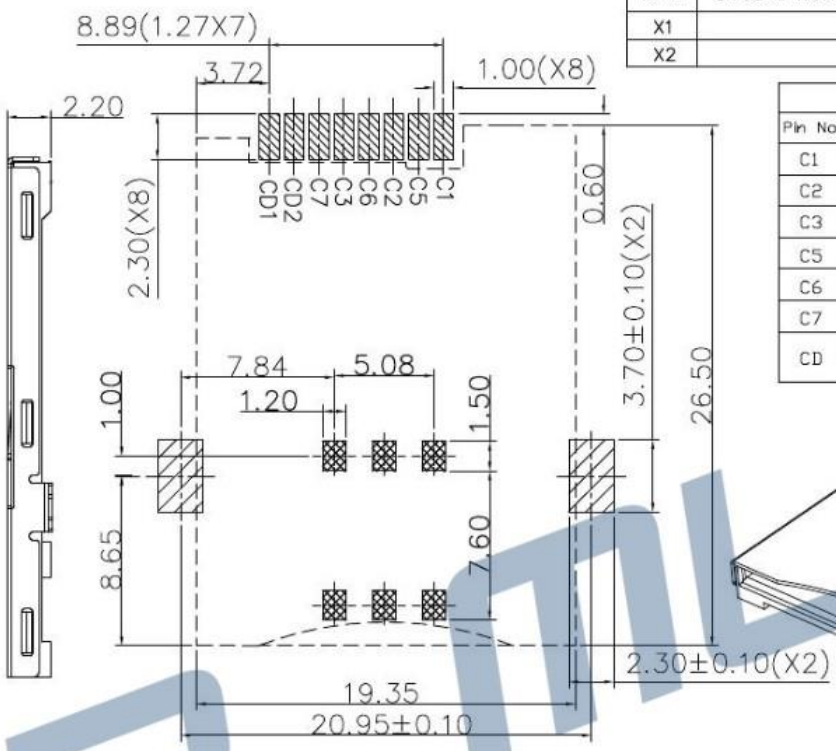
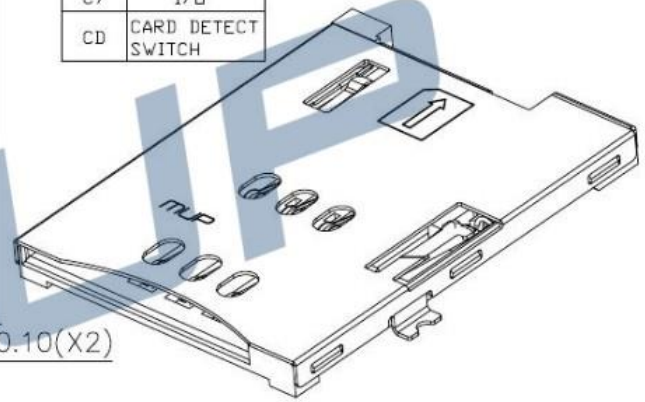
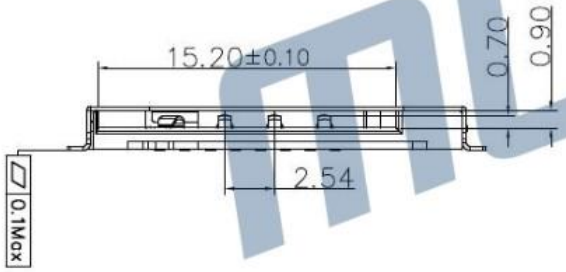
REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					
X2					







SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O
CD	CARD DETECT SWITCH



RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)
PAD AREA
CONNECTOR OUTLINE
NO PATTERN AND VIA HOLE IN THIS AREA

TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: 26.50LX19.35WX2.20H mm

Weight: Approx 1.50±0.1g

Durability: 3,000 cycles min.

2.Electrical Characteristics

Contact resistance: 50mΩ typical,100mΩ max

Insulation resistance: >1000MΩ/500V DC

3.Solderability

Vapor phase: 215°C,30sec.Max

IR reflow: 250°C,5sec.Max

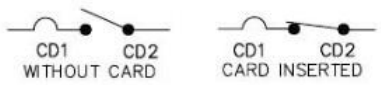
Manual soldering: 370°C,3sec.Max

4.Environmental Characteristics

Operating temperature: −40°C~+85°C

Operating humidity: 10%~+95%RH

ELECTRIC FUNCTION	DETECT SWITCH
WITHOUT CARD	OPEN
CARD INSERTED	CLOSED



SWITCH OPERATION DIAGRAM

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi−temp Thermoplastic	Black UL94V−0
2	DATA CONTACT	6	Copper Alloy	Contact area Au plated, Tin plating on solder tails.
3	SHELL	1	Stainless Steel	SMT area:Au plated
4	COIL SPRING	1	SWP	
5	HEART CAM	1	Hi−temp Thermoplastic	Black UL94V−0
6	CAM PIN	1	Stainless Steel	
7	SWITCH CONTACT 1	1	Copper Alloy	Contact&solder area:Au plated
8	SWITCH CONTACT 2	1	Copper Alloy	Contact&solder area:Au plated

Unless otherwise specified, other tolerance are:

X ±0.35	X° ±5°		
X.X ±0.25	X.X° ±4°		
X.XX ±0.15	X.XX° ±3°		
X.XXX ±0.10	X.XXX° ±2°		

MUP® MUP INDUSTRIAL CO.,LTD.

NAME:	SIM Card Connector
MODEL NO:	MUP-C760-2
TYPE :	H2.20 mm without post

PROJ.	UNIT	SCALE
	mm	1:1

CUSTOMER DRAWING

DRAWN	Henry Jul.08.2016	DWG NO.	DWG−MUP−C760−2
CHECKED	Henry Jul.08.2016	SHEET 1/1	REVISION X1
APPROVAL	Simon Jul.08.2016		

MUP MUP